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(54) MANUFACTURE OF MULTILAYER PRINTED
WIRING BOARD

conductive metallic foils 1a, 1b being positioned as
outer layers.

(57) Abstract:

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PROBLEM TO BE SOLVED: To provide a method for manufacturing high-reliability printed wiring boards with a high yield rate capable of performing high-density wiring and packaging, simplifying the manufacturing process.

SOLUTION: First of all, the main surface of a synthetic resin sheet 4a is opposed to the wiring pattern 2a forming surface of a wiring raw board 3 having a conductive metal foil 1a on one main surface and having a wiring pattern 2a on the other main surface, and arranged like a laminate. Next a conductive metal foil 1b having conductive bumps 5a for forming electric connections with the wiring pattern 2a on one main surface is positioned, arranged, and laminated on the main surface of the synthetic resin sheet 4a. And pressure is applied to the laminated substance, and the tips of the conductive bumps 5a are inserted into the synthetic resin sheet in the direction of its thickness, and a through type conductor wiring part 5 for the wiring pattern 2a opposed is formed. And wiring patterning 2b is performed by selectively etching both

